

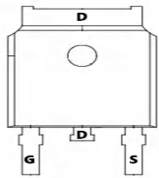
TMG12N12D

N-Channel Enhancement Mosfet

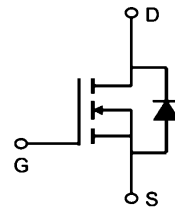
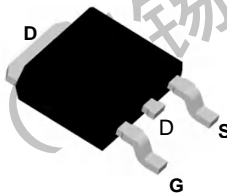
<p>General Description</p> <ul style="list-style-type: none"> • Low $R_{DS(ON)}$ • RoHS and Halogen-Free Compliant <p>Applications</p> <ul style="list-style-type: none"> • Load switch • PWM 	<p>General Features</p> <p>$V_{DS} = 120V$ $I_D = 12A$</p> <p>$R_{DS(ON)} = 85m\Omega (typ.) @ V_{GS} = 10V$</p> <p>100% UIS Tested 100% R_g Tested</p>
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D:TO-252-3L



Marking G12N12



Absolute Maximum Ratings ($T_C = 25^\circ C$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	120	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	12	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	8.7	A
I_{DM}	Pulsed Drain Current	60	A
EAS	Single Pulse Avalanche Energy	22	mJ
$P_D @ T_C = 25^\circ C$	Total Power Dissipation	46	W
T_{STG}	Storage Temperature Range	-55 to 175	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 175	$^\circ C$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient	---	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case	---	6.6	$^\circ C/W$



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Electrical Characteristics (T_J= 25°C unless otherwise specified) :

Static Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
V _{DSS}	Drain to Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	120	--	--	V
I _{DSS}	Drain to Source Leakage Current	V _{DS} = 100V, V _{GS} = 0V	--	--	1	μA
I _{GSS(F)}	Gate to Source Forward Leakage	V _{GS} =-20V	--	--	100	nA
I _{GSS(R)}	Gate to Source Reverse Leakage	V _{GS} =+20V	--	--	-100	nA
V _{GS(TH)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	2.0	2.5	3.0	V
R _{DS(ON)}	Drain-to-Source On-Resistance	V _{GS} =10V, I _D =5A	--	85	99	mΩ
		V _{GS} =4.5V, I _D =4A	--	--	--	mΩ

Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
C _{iss}	Input Capacitance	V _{GS} =0V V _{DS} =50V f=1.0MHz	--	248	--	pF
C _{oss}	Output Capacitance		--	60	--	
C _{rss}	Reverse Transfer Capacitance		--	2.0	--	

Resistive Switching Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
t _{d(ON)}	Turn-on Delay Time	I _D =10A, R _L =0.75Ω V _{DS} =50V V _{GS} = 10V R _G = 3Ω	--	9	--	ns
t _r	Rise Time		--	18	--	
t _{d(OFF)}	Turn-Off Delay Time		--	19	--	
t _f	Fall Time		--	16	--	
Q _g	Total Gate Charge	V _{GS} =10V	--	3.8	--	nC
Q _{gs}	Gate Source Charge	V _{DS} =50V	--	0.9	--	
Q _{gd}	Gate Drain Charge	I _D =10A	--	1	--	

Source-Drain Diode Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
I _S	Diode Forward Current	T _C =25 °C	--	--	12	A
V _{SD}	Diode Forward Voltage	I _S =0.5A, V _{GS} =0V	--	--	1.2	V
t _{rr}	Reverse Recovery time	I _S =10A, V _{DD} =50V di/dt=100A/μs	--	24	--	ns
Q _{rr}	Reverse Recovery Charge		--	20	--	nC

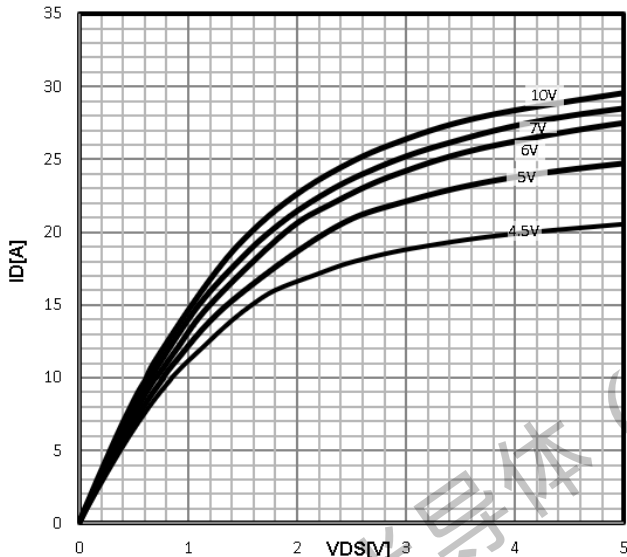


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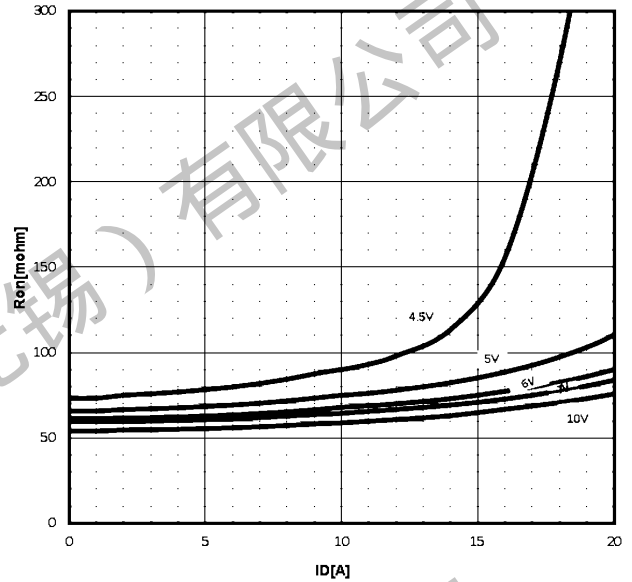
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Characteristics Curve:

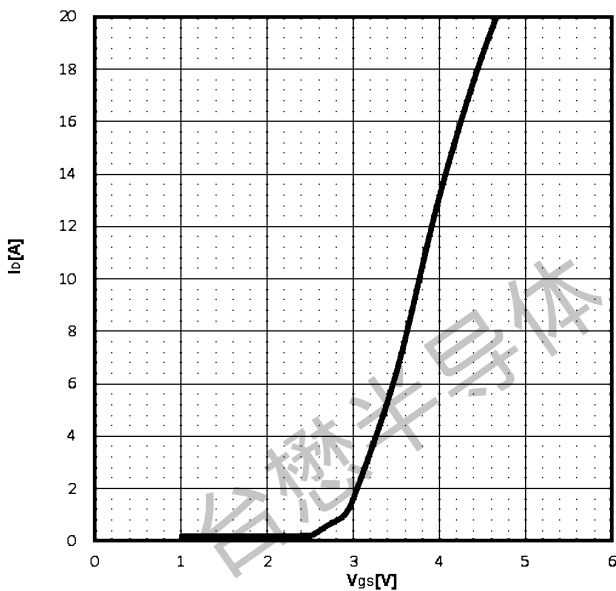
Typ. output characteristics
 $I_D=f(V_{DS})$



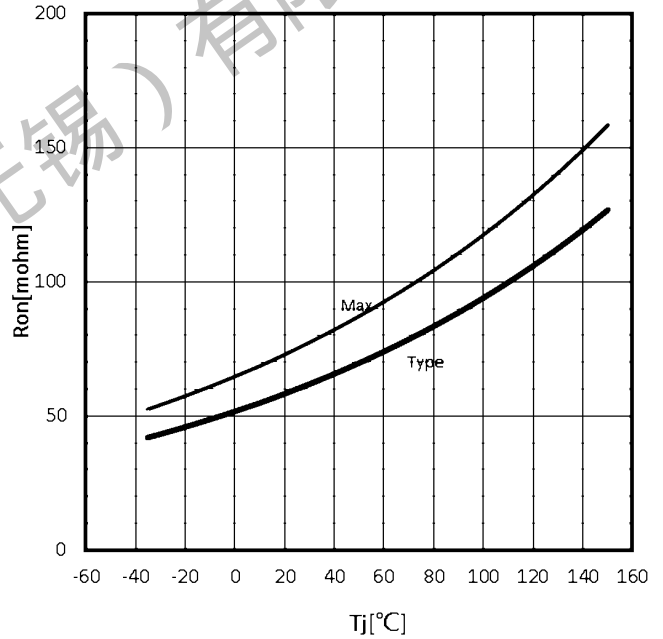
Typ. drain-source on resistance
 $R_{DS(on)}=f(I_D)$



Typ. transfer characteristics
 $I_D=f(V_{GS})$



Drain-source on-state resistance
 $R_{DS(on)}=f(T_j); I_D=5A; V_{GS}=10V$

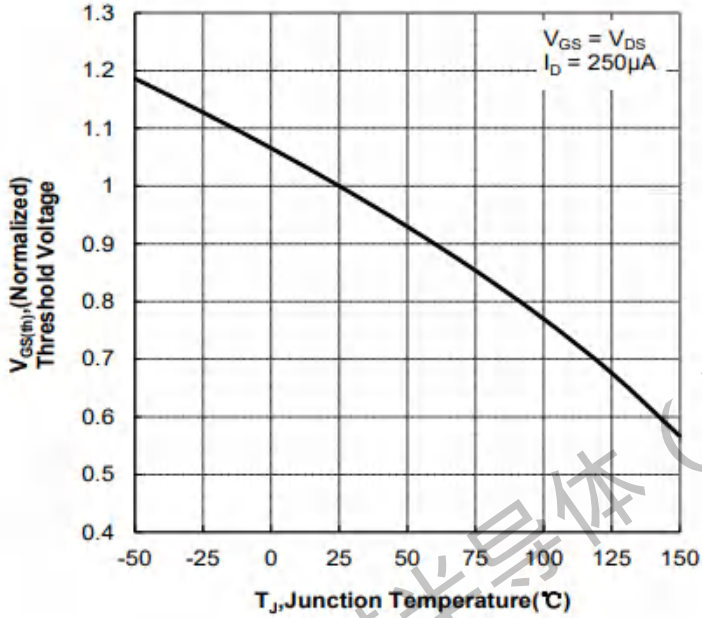




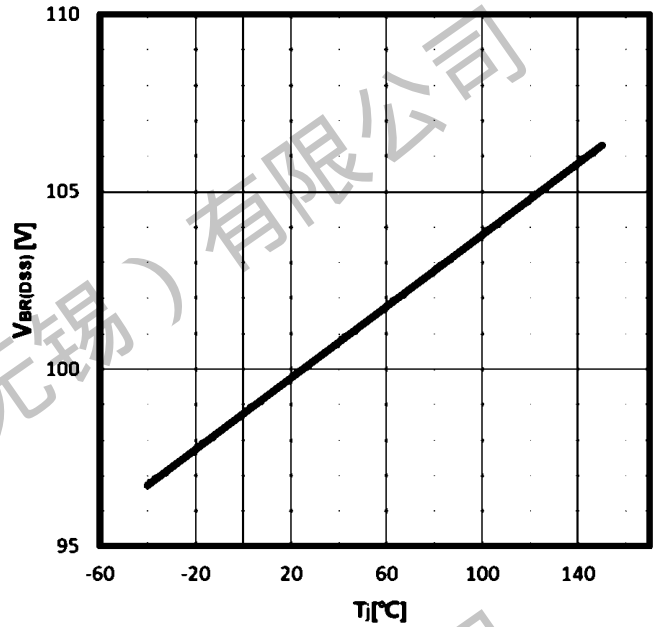
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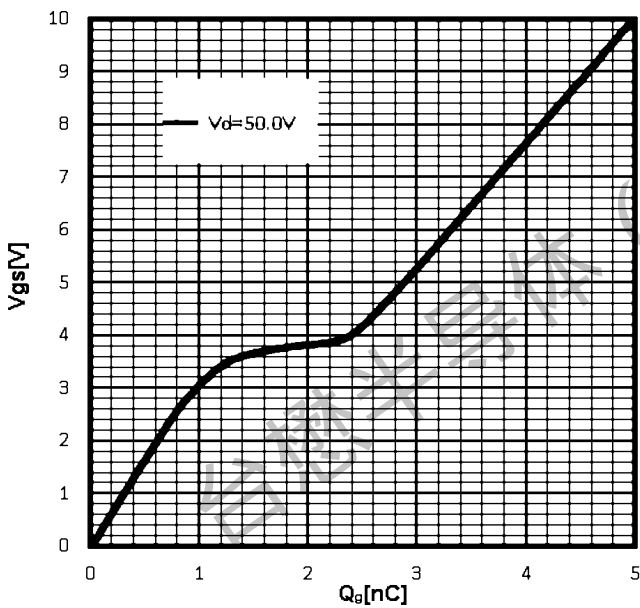
Gate Threshold Voltage
 $V_{TH}=f(T_j)$; $I_D=250\mu A$



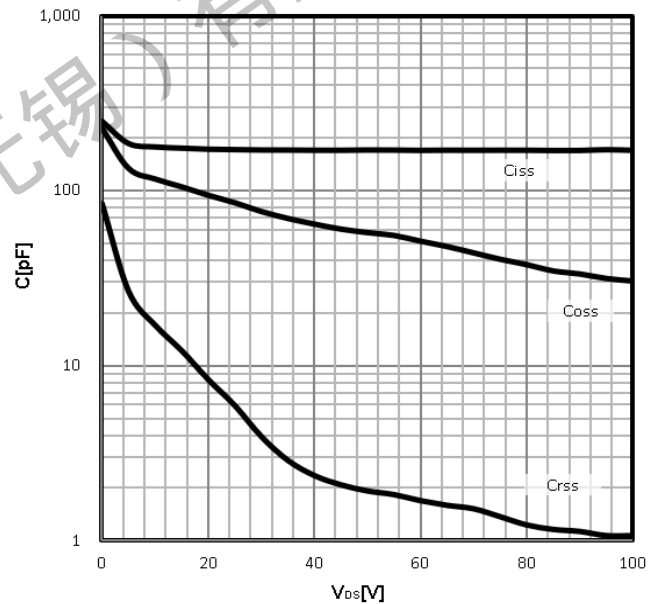
Drain-source breakdown voltage
 $V_{BR(DSS)}=f(T_j)$; $I_D=250\mu A$



Typ. gate charge
 $V_{GS}=f(Q_g)$; $I_D=10A$



Typ. capacitances
 $C=f(V_{DS})$; $V_{GS}=0V$; $f=1MHz$



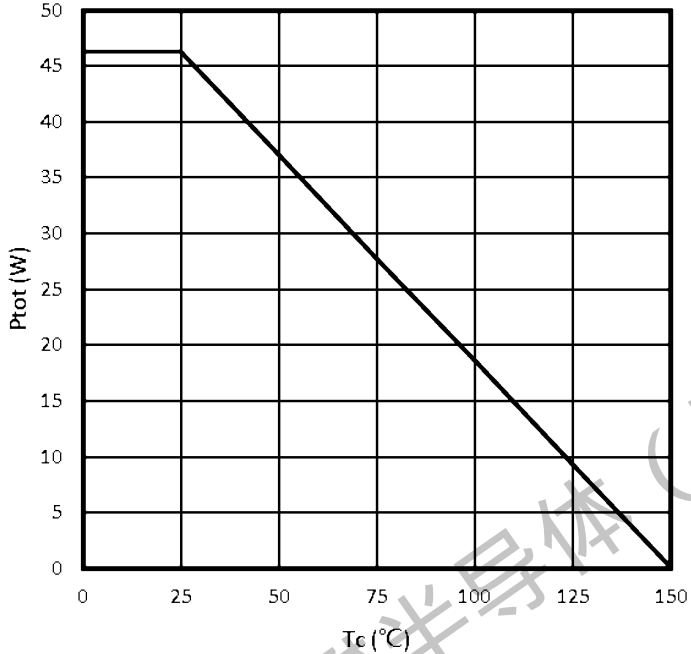


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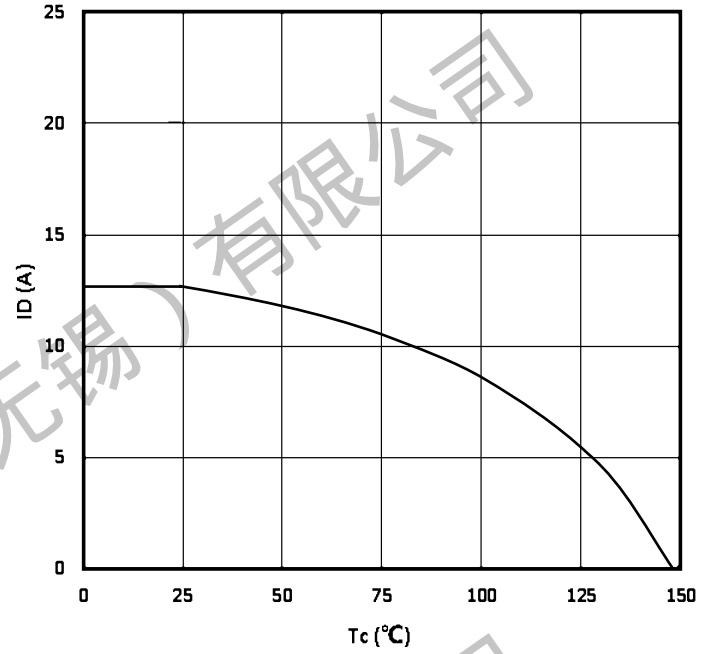
Power Dissipation

$P_{tot}=f(T_c)$



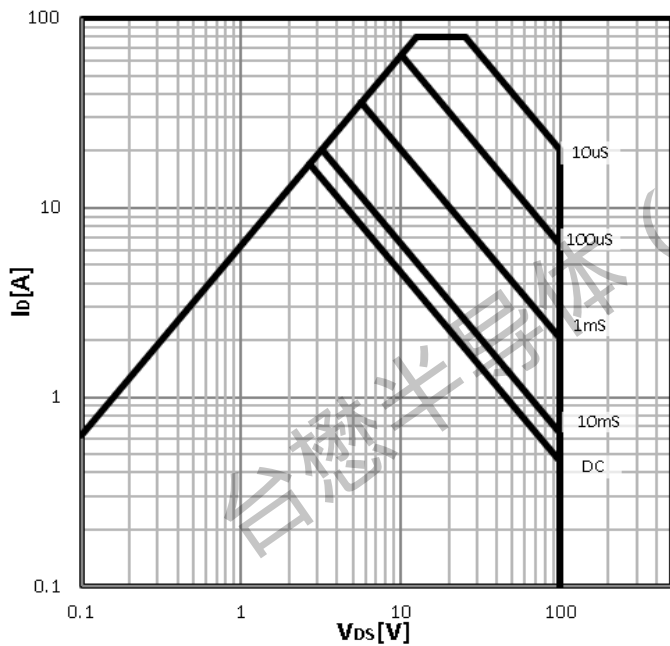
Maximum Drain Current

$I_D=f(T_c)$



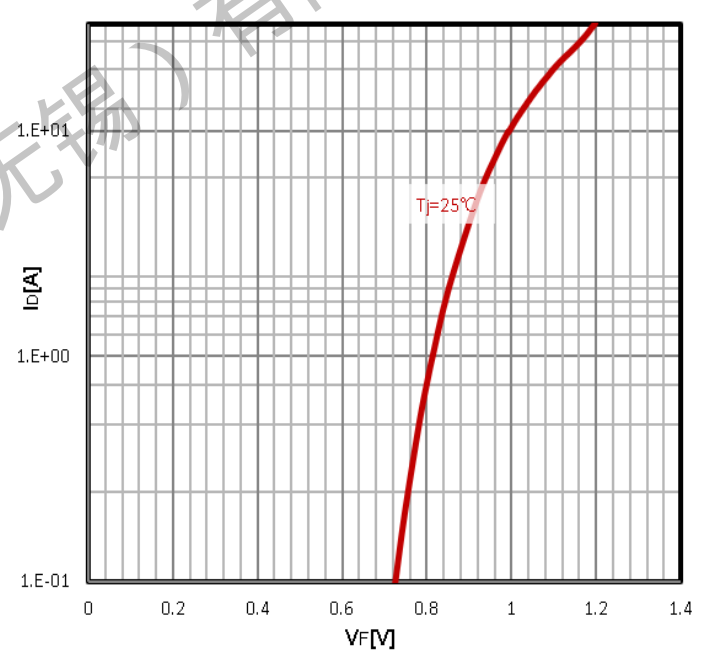
Safe operating area

$I_D=f(V_{DS})$



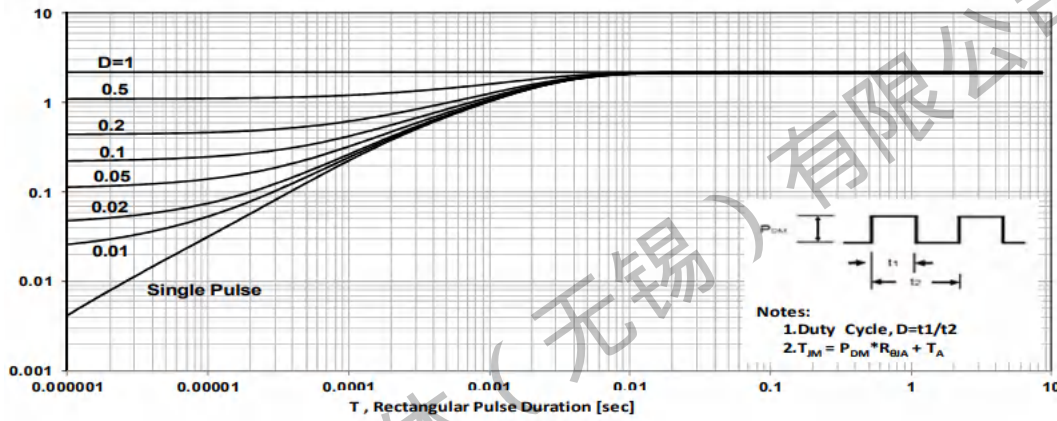
Body Diode Forward Voltage Variation

$I_F=f(V_{GS})$



Max. transient thermal impedance

$$Z_{thJC} = f(t_p)$$



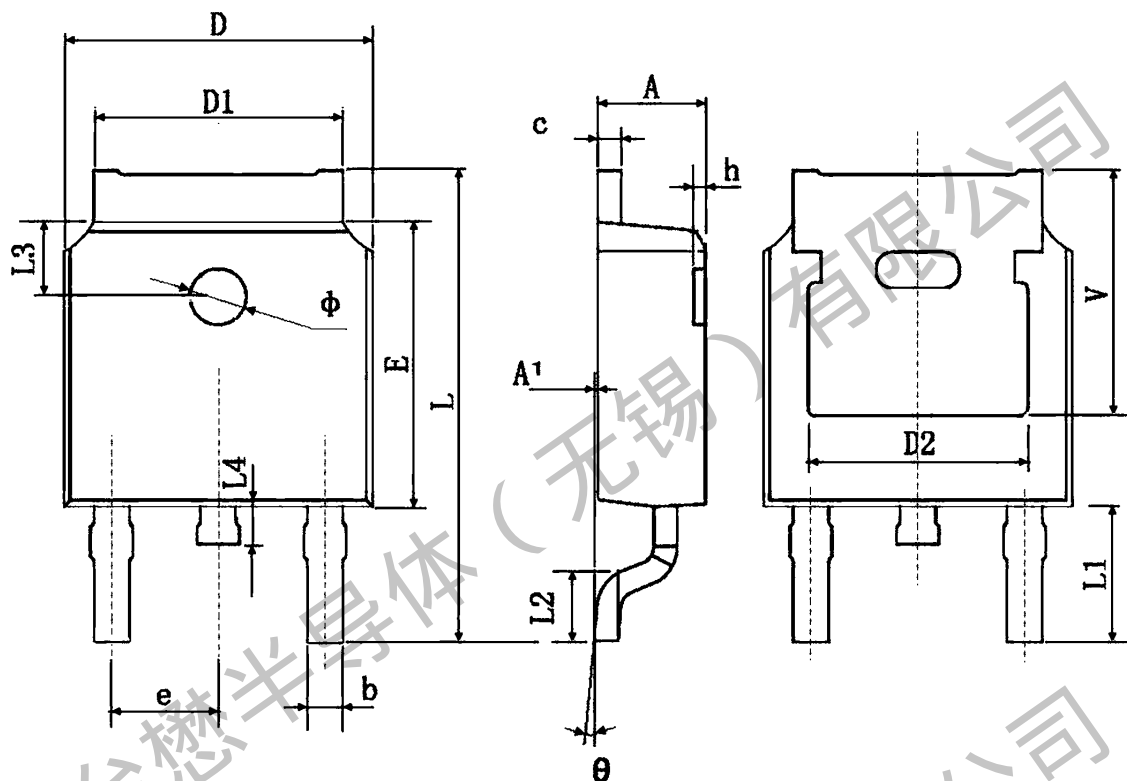
台懋半导体(无锡)有限公司



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Package Mechanical Data: TO-252-3L



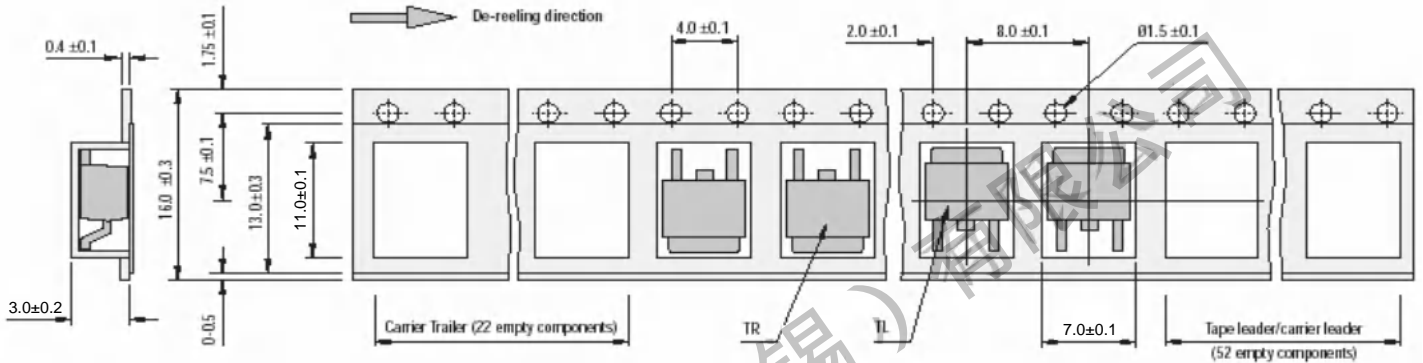
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	



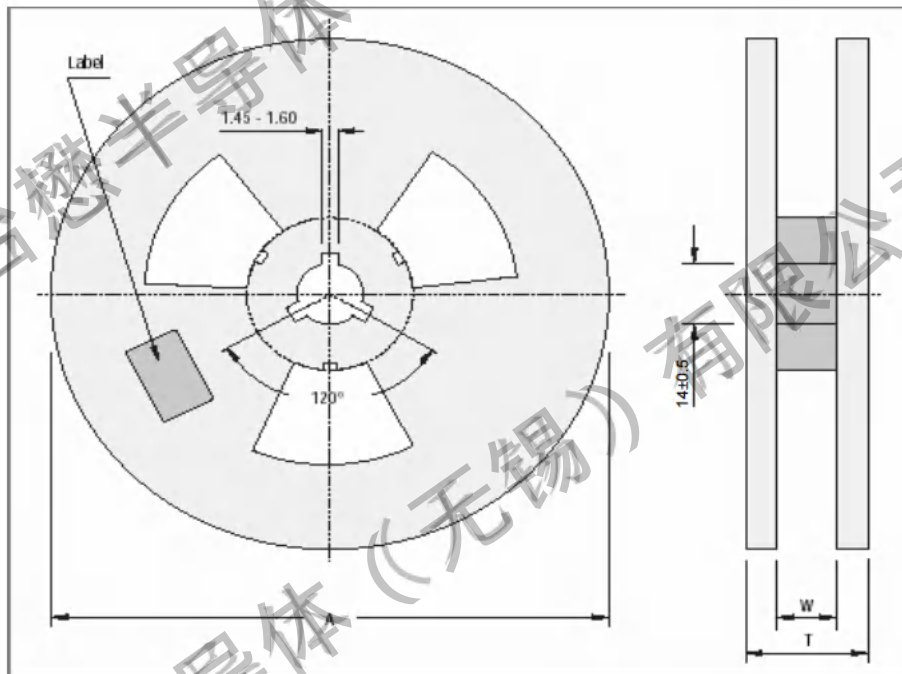
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TO-252-3L Embossed Carrier Tape



TO-252-3L Reel



All Dimensions are in mm

Reel Specifications				
Package	Tape Width	Reel Dia. A - Max	Inside Thickness W	Reel Thickness T - max
TO-252-3L	16	330	18.0 ±1.5	20

Packaging Information

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
2,500 pcs	13 inch	5,000 pcs	355×370×50	25,000 pcs	380×275×380	



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Revision history:

Date	Rev	Description	Page
2024.12.23	24.12	Original	